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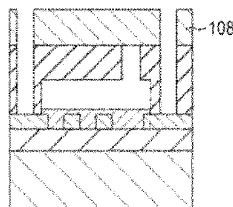
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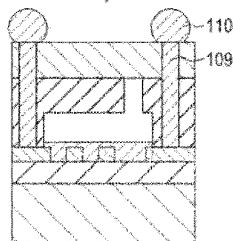
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(54) Title: METHOD OF MANUFACTURING ACOUSTIC WAVE DEVICE



1-j



1-k

Fig. 1B

(57) Abstract: A method of manufacturing an acoustic wave device according to the present invention comprises the steps of: forming an electrode on a piezoelectric substrate; forming a protective layer frame body surrounding the electrode; forming a sacrificial layer on the electrode by applying a sacrificial liquid thereon; forming a protective layer lid body on the sacrificial layer; and heating and removing the sacrificial layer to form an air gap, wherein the sacrificial liquid comprises a polymer and a solvent, and the polymer has a glass transition temperature of from 0 to 180°C.

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